Dooket No.: NECW 18.159

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor:

Atsushi NISHIZAWA

Serial No.:

09/751,979

Filed:

December 29, 2000

Title:

MANUFACTURING METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT INCLUDING SIMULTANEOUS FORMATION OF VIA HOLE REACHING METAL WIRING AND CONCAVE GROOVE IN INTERLAYER FILM AND

TECHNOLOGY CENTER 1700 SEMICONDUCTOR INTEGRATED CIRCUIT MANUFACTURED

WITH THE MANUFACTURING METHOD

Examiner:

George A. Goudreau

Group Art Unit:

1763

Assistant Commission for Patents Washington, D.C. 20231

CHANGE IN CORRESPONDENCE ADDRESS

SIR:

It is respectfully requested that any future correspondence regarding the above-referenced application be directed to Applicant's attorneys (previously appointed) at the following new correspondence address:

> Katten Muchin Zavis Rosenman 575 Madison Avenue New York, New York 10022

Phone: (212) 940-8800

Fax: (212) 940-8986 or (212) 940-8987

Any inquiries regarding this change in address may be directed to the Applicant's undersigned attorney at the above-referenced telephone numbers.

Our CUSTOMER NUMBER 026304 remains the same.

, EV0964208851

KATTEN MUCHIN ZAVIS ROSENMAN **575 MADISON AVENUE** NEW YORK, NEW YORK 10022 (212) 940-8687 DOCKET NO.: NECW 18.159

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